

Docket No. 50439-2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Barstad et al.

SERIAL NO.: 09/605,442

EXAMINER: W. Nicholas

FILED: June 28, 2000

GROUP: 1742

FOR: ELECTROLYTIC COPPER PLATING SOLUTIONS

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RESPONSE TO FINAL OFFICE ACTION

Applicants are in receipt of and respond as follows to the Final Office Action dated July 9, 2003.

Claims 124-136 were rejected under 35 U.S.C. 102(e) over Landau et al. (U.S. Patent 6,379,522).

Claims 137-153 were rejected under 35 U.S.C. 103 over Landau et al. (U.S. Patent 6,379,522) in view of Dahms et al. (U.S. Patent 5,433,840).

For the sake of brevity, the two rejections are addressed in combination. Such a combined response is considered appropriate because, *inter alia*, each of the rejections relies on the Landau et al. as the sole or primary citation.

While Applicants disagree with the rejections, including for reasons set forth in Applicants' prior response, submitted herewith is a Rule 131 Declaration which effectively antedates the Landau et al. citation.